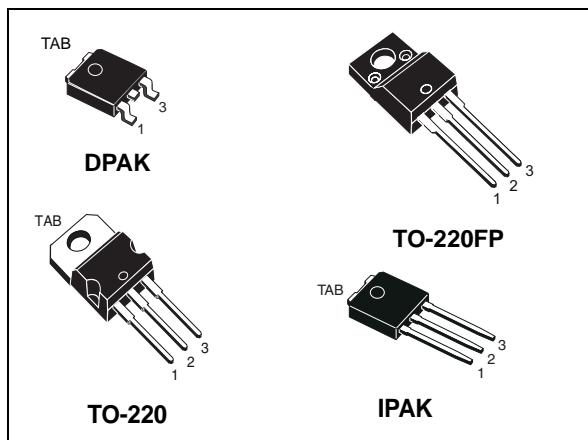


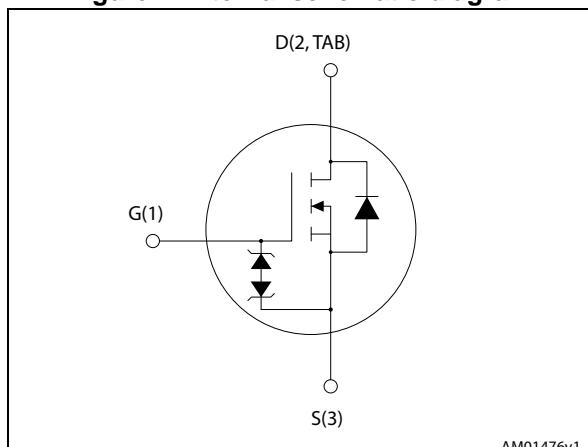
# STD2N80K5, STF2N80K5, STP2N80K5, STU2N80K5

N-channel 800 V, 3.5  $\Omega$  typ., 2 A MDmesh™ K5 Power MOSFETs  
in DPAK, TO-220FP, TO-220 and IPAK packages

Datasheet – production data



**Figure 1. Internal schematic diagram**



## Features

Order codes	V <sub>DS</sub>	R <sub>DS(on)max</sub>	I <sub>D</sub>	P <sub>TOT</sub>
STD2N80K5	800 V	4.5 $\Omega$	2 A	45 W
STF2N80K5				20 W
STP2N80K5				
STU2N80K5				45 W

- Industry's lowest R<sub>DS(on)</sub> \* area
- Industry's best figure of merit (FoM)
- Ultra low gate charge
- 100% avalanche tested
- Zener-protected

## Applications

- Switching applications

## Description

These very high voltage N-channel Power MOSFETs are designed using MDmesh™ K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

**Table 1. Device summary**

Order codes	Marking	Package	Packaging
STD2N80K5	2N80K5	DPAK	Tape and reel
STF2N80K5		TO-220FP	Tube
STP2N80K5		TO-220	
STU2N80K5		IPAK	

## Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		DPAK, TO-220, IPAK	TO-220FP	
$V_{GS}$	Gate- source voltage	30		V
$I_D$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	2 <sup>(1)</sup>		A
$I_D$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	1.3		A
$I_{DM}^{(2)}$	Drain current (pulsed)	8		A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$	45	20	W
$I_{AR}$	Max current during repetitive or single pulse avalanche (pulse width limited by $T_{jmax}$ )	0.5		A
$E_{AS}$	Single pulse avalanche energy (starting $T_J = 25^\circ\text{C}$ , $I_D=I_{AS}$ , $V_{DD}= 50\text{ V}$ )	60.5		mJ
$dv/dt^{(3)}$	Peak diode recovery voltage slope	4.5		V/ns
$dv/dt^{(4)}$	MOSFET dv/dt ruggedness	50		V/ns
$T_j$	Operating junction temperature	-55 to 150		$^\circ\text{C}$
$T_{stg}$	Storage temperature			$^\circ\text{C}$

1. For TO-220FP limited by maximum junction temperature.
2. Pulse width limited by safe operating area.
3.  $I_{SD} \leq 2\text{ A}$ ,  $dI/dt \leq 100\text{ A}/\mu\text{s}$ , peak  $V_{DS} \leq V_{(BR)DSS}$
4.  $V_{DS} \leq 640\text{ V}$

**Table 3. Thermal data**

Symbol	Parameter	Value				Unit
		DPAK	TO-220FP	TO-220	IPAK	
$R_{thj-case}$	Thermal resistance junction-case	2.78	6.25	2.78	2.78	$^\circ\text{C/W}$
$R_{thj-pcb}$	Thermal resistance junction-pcb	50 <sup>(1)</sup>				
$R_{thj-amb}$	Thermal resistance junction-amb			62.5	100	

1. When mounted on FR-4 board of 1 inch<sup>2</sup>, 2 oz Cu.

## 2 Electrical characteristics

( $T_{CASE} = 25^\circ\text{C}$  unless otherwise specified).

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage ( $V_{GS} = 0$ )	$I_D = 1 \text{ mA}$	800			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = 800 \text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 800 \text{ V } T_C=125^\circ\text{C}$			50	$\mu\text{A}$
$I_{GSS}$	Gate body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20 \text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 100 \mu\text{A}$	3	4	5	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 1 \text{ A}$		3.5	4.5	$\Omega$

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100 \text{ V}, f=1 \text{ MHz}, V_{GS}=0$	-	105	-	pF
$C_{oss}$	Output capacitance		-	8	-	pF
$C_{rss}$	Reverse transfer capacitance		-	0.5	-	pF
$C_{o(tr)}^{(1)}$	Equivalent capacitance time related	$V_{GS} = 0, V_{DS} = 0 \text{ to } 640 \text{ V}$	-	16	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related		-	7	-	pF
$R_G$	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D=0$	-	18	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 640 \text{ V}, I_D = 2 \text{ A}$ $V_{GS} = 10 \text{ V}$	-	5	-	nC
$Q_{gs}$	Gate-source charge		-	1	-	nC
$Q_{gd}$	Gate-drain charge		-	3.7	-	nC

1. Time related is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

2. Energy related is defined as a constant equivalent capacitance giving the same stored energy as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 400 \text{ V}, I_D = 1 \text{ A}, R_G=4.7 \Omega, V_{GS}=10 \text{ V}$	-	8	-	ns
$t_r$	Rise time		-	12	-	ns
$t_{d(off)}$	Turn-off delay time		-	19	-	ns
$t_f$	Fall time		-	32	-	ns

**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		2	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		8	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 2 \text{ A}, V_{GS}=0$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 2 \text{ A}, V_{DD} = 60 \text{ V}$ $dI/dt = 100 \text{ A}/\mu\text{s},$	-	255		ns
$Q_{rr}$	Reverse recovery charge		-	1		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	8		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 2 \text{ A}, V_{DD} = 60 \text{ V}$ $dI/dt=100 \text{ A}/\mu\text{s},$ $T_j=150^\circ\text{C}$	-	285		ns
$Q_{rr}$	Reverse recovery charge		-	1.45		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	7.5		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

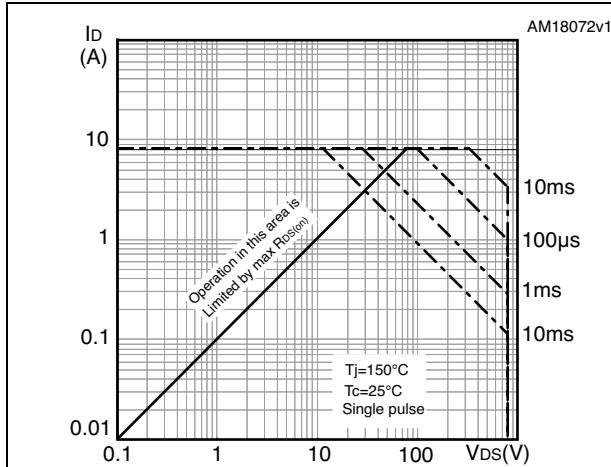
**Table 8. Gate-source Zener diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1 \text{ mA}, I_D = 0$	30	-	-	V

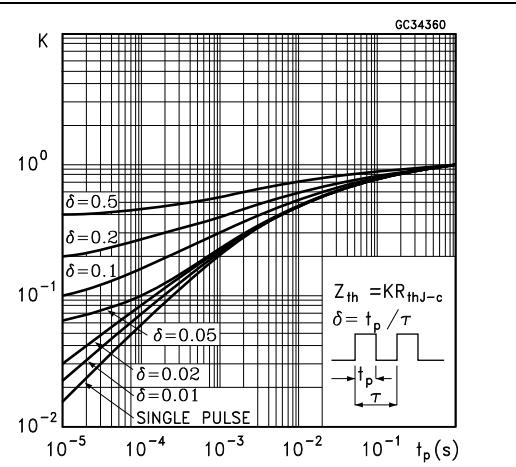
The built-in back-to-back Zener diodes have been specifically designed to enhance the ESD capability of the device. The Zener voltage is appropriate for efficient and cost-effective intervention to protect the device integrity. These integrated Zener diodes thus eliminate the need for external components.

## 2.1 Electrical characteristics (curves)

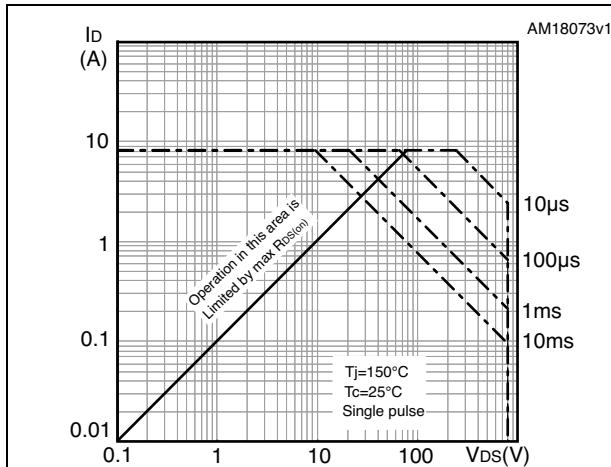
**Figure 2. Safe operating area for DPAK and IPAK**



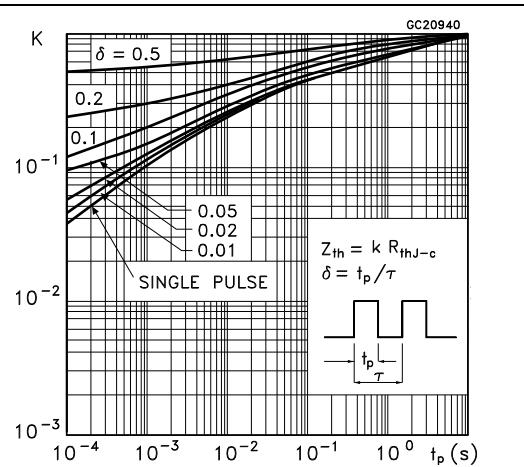
**Figure 3. Thermal impedance for DPAK and IPAK**



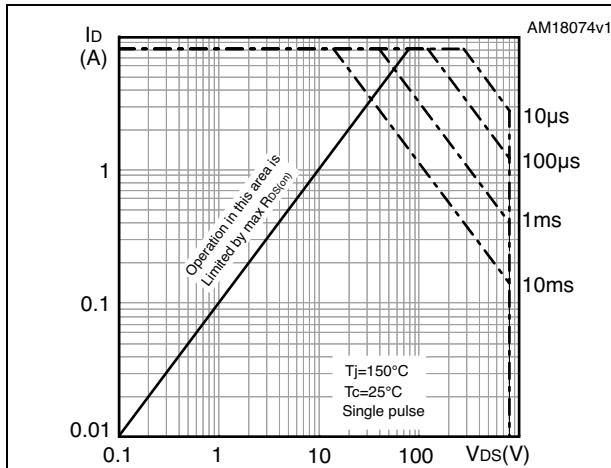
**Figure 4. Safe operating area for TO-220FP**



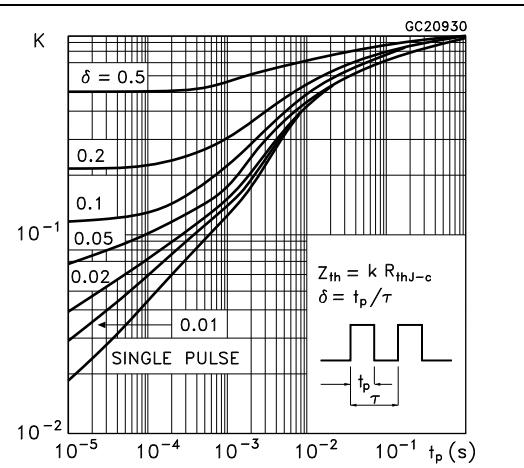
**Figure 5. Thermal impedance for TO-220FP**

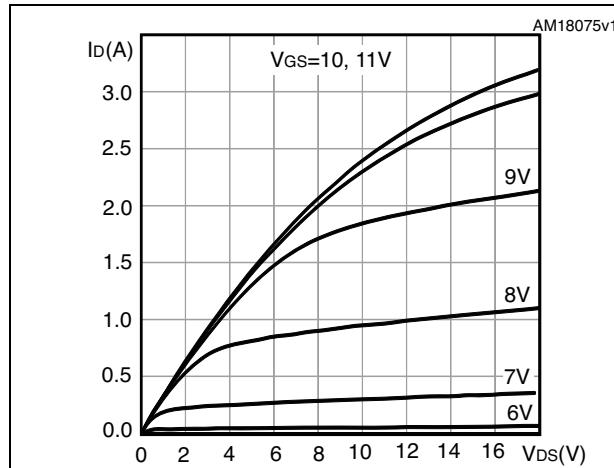
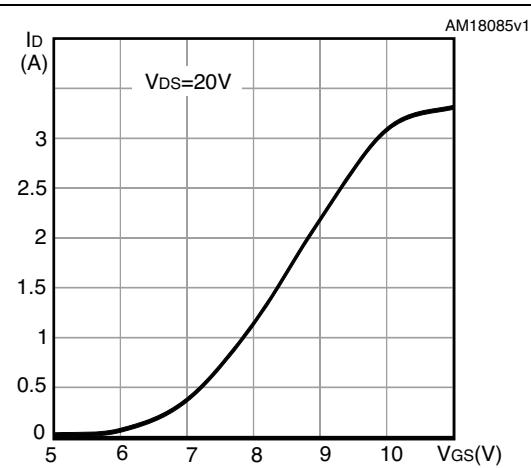
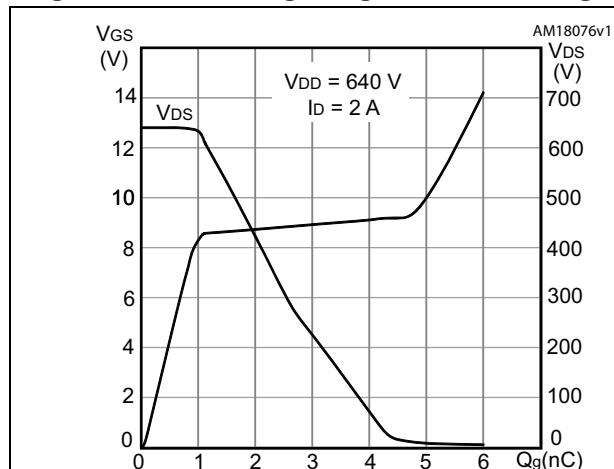
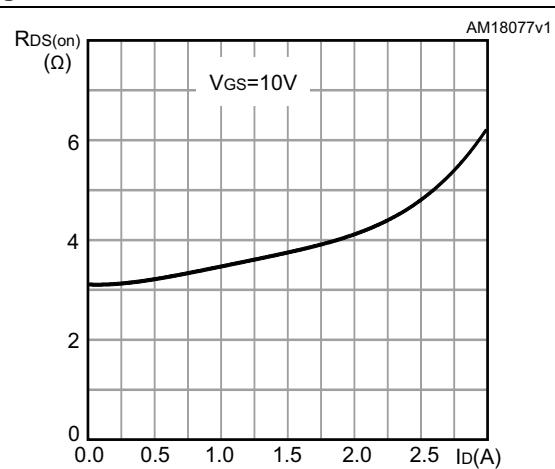
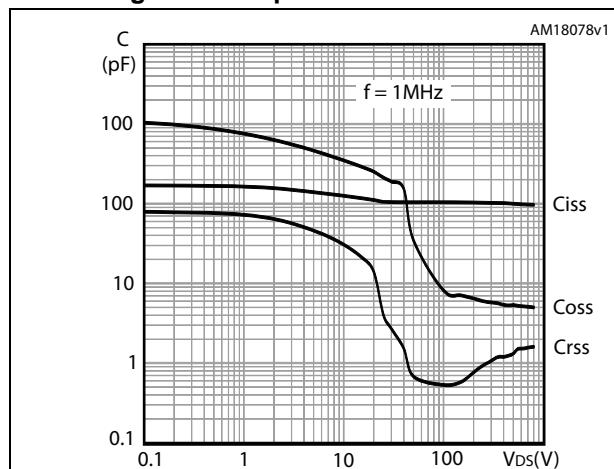
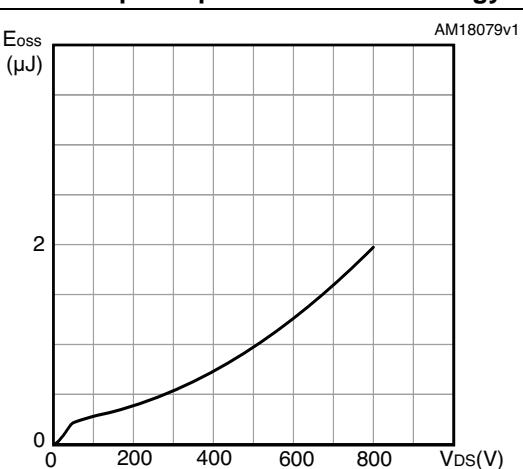


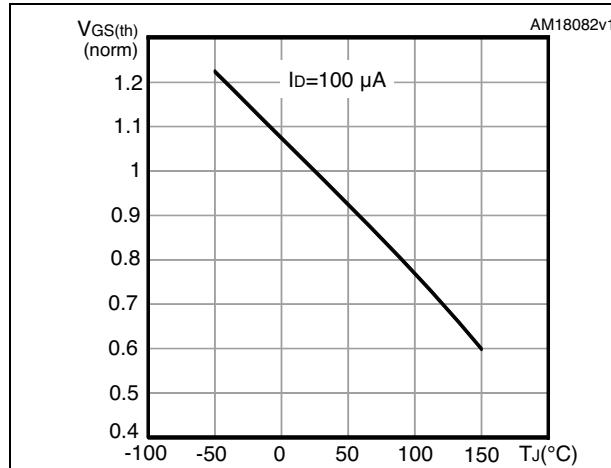
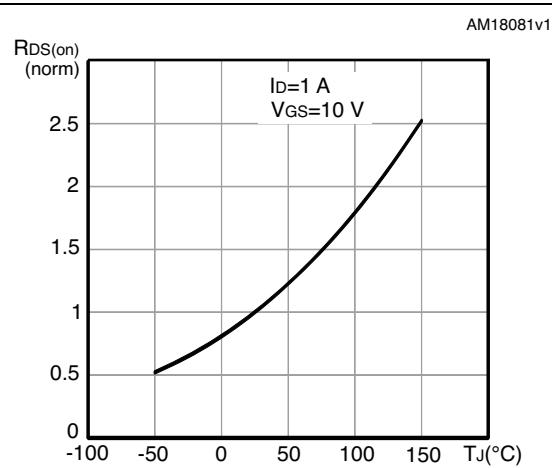
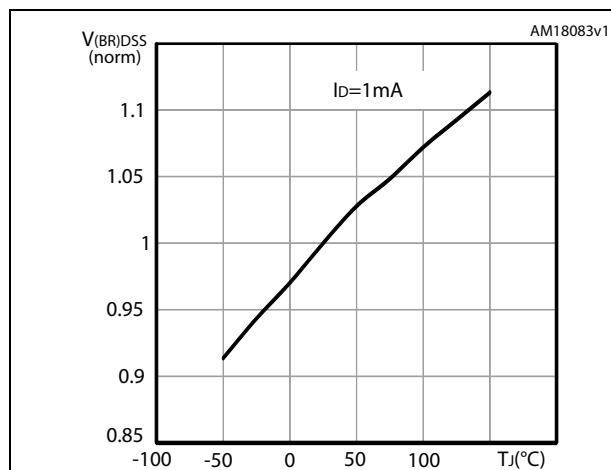
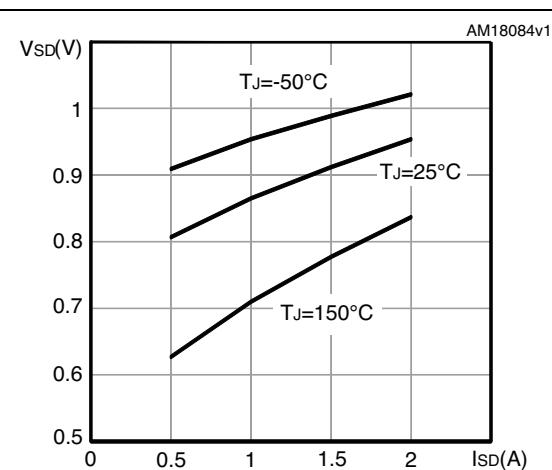
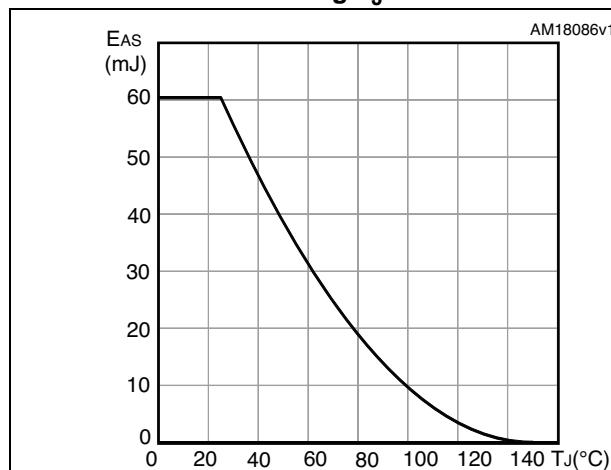
**Figure 6. Safe operating area for TO-220**



**Figure 7. Thermal impedance for TO-220**

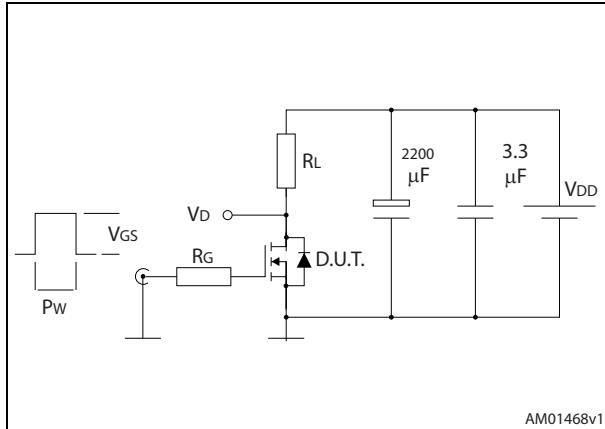


**Figure 8. Output characteristics****Figure 9. Transfer characteristics****Figure 10. Gate charge vs gate-source voltage****Figure 11. Static drain-source on-resistance****Figure 12. Capacitance variations****Figure 13. Output capacitance stored energy**

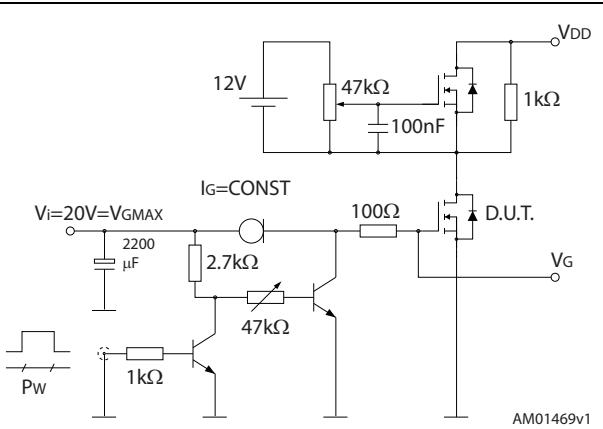
**Figure 14. Normalized gate threshold voltage vs temperature****Figure 15. Normalized on-resistance vs temperature****Figure 16. Normalized V<sub>(BR)DSS</sub> vs temperature****Figure 17. Source-drain diode forward characteristics****Figure 18. Maximum avalanche energy vs starting T<sub>J</sub>**

### 3 Test circuits

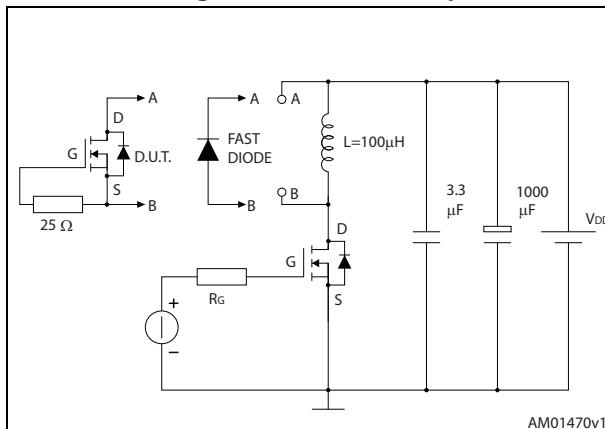
**Figure 19. Switching times test circuit for resistive load**



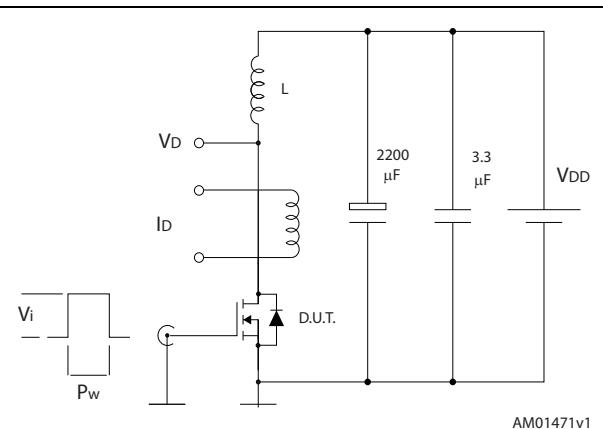
**Figure 20. Gate charge test circuit**



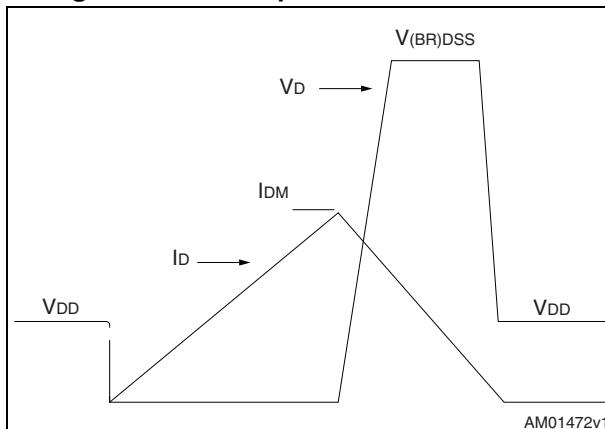
**Figure 21. Test circuit for inductive load switching and diode recovery times**



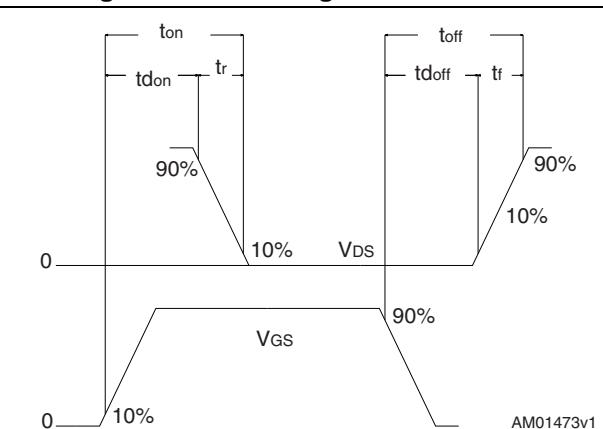
**Figure 22. Unclamped inductive load test circuit**



**Figure 23. Unclamped inductive waveform**



**Figure 24. Switching time waveform**

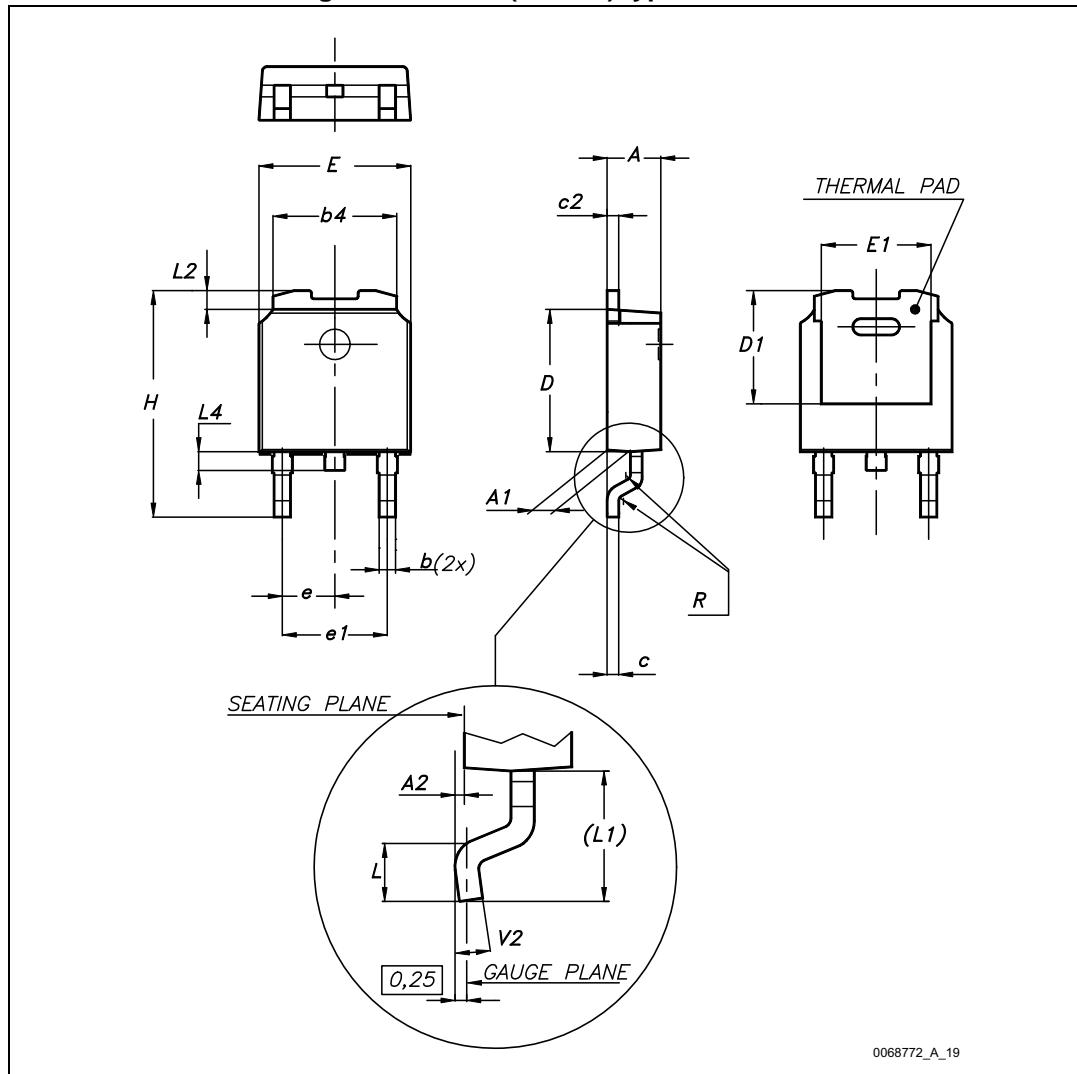


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
ECOPACK® is an ST trademark.

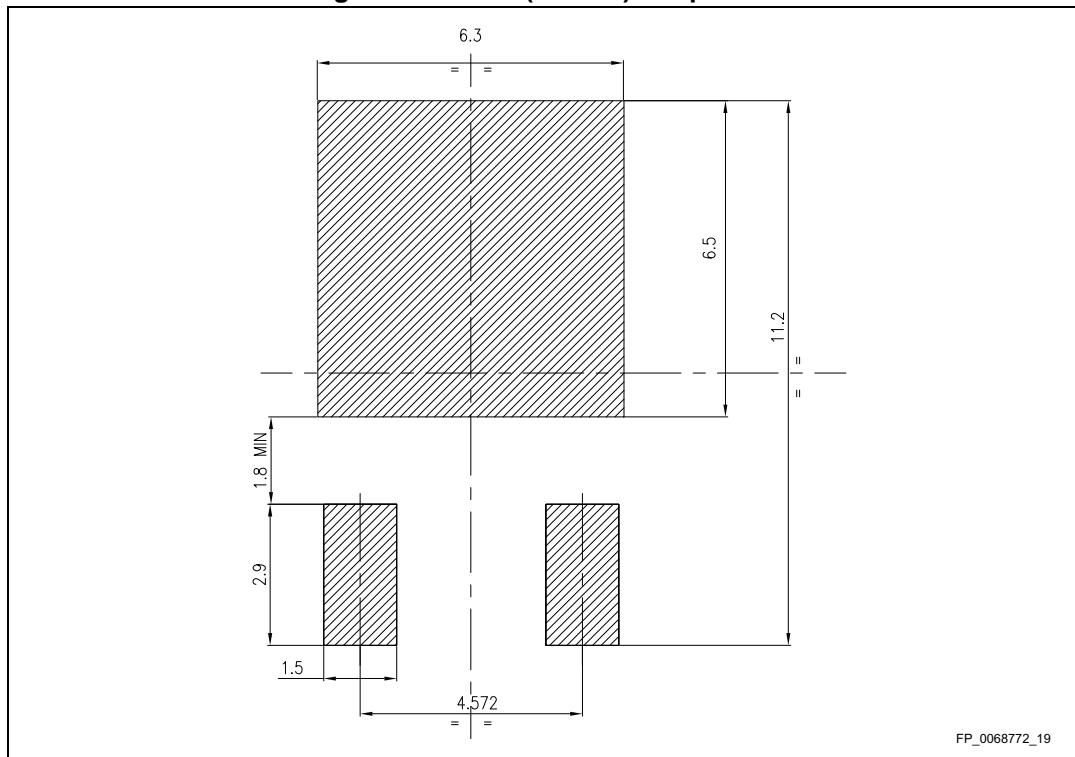
### 4.1 DPAK (TO-252) type A package information

Figure 25. DPAK (TO-252) type A outline



**Table 9. DPAK (TO-252) type A mechanical data**

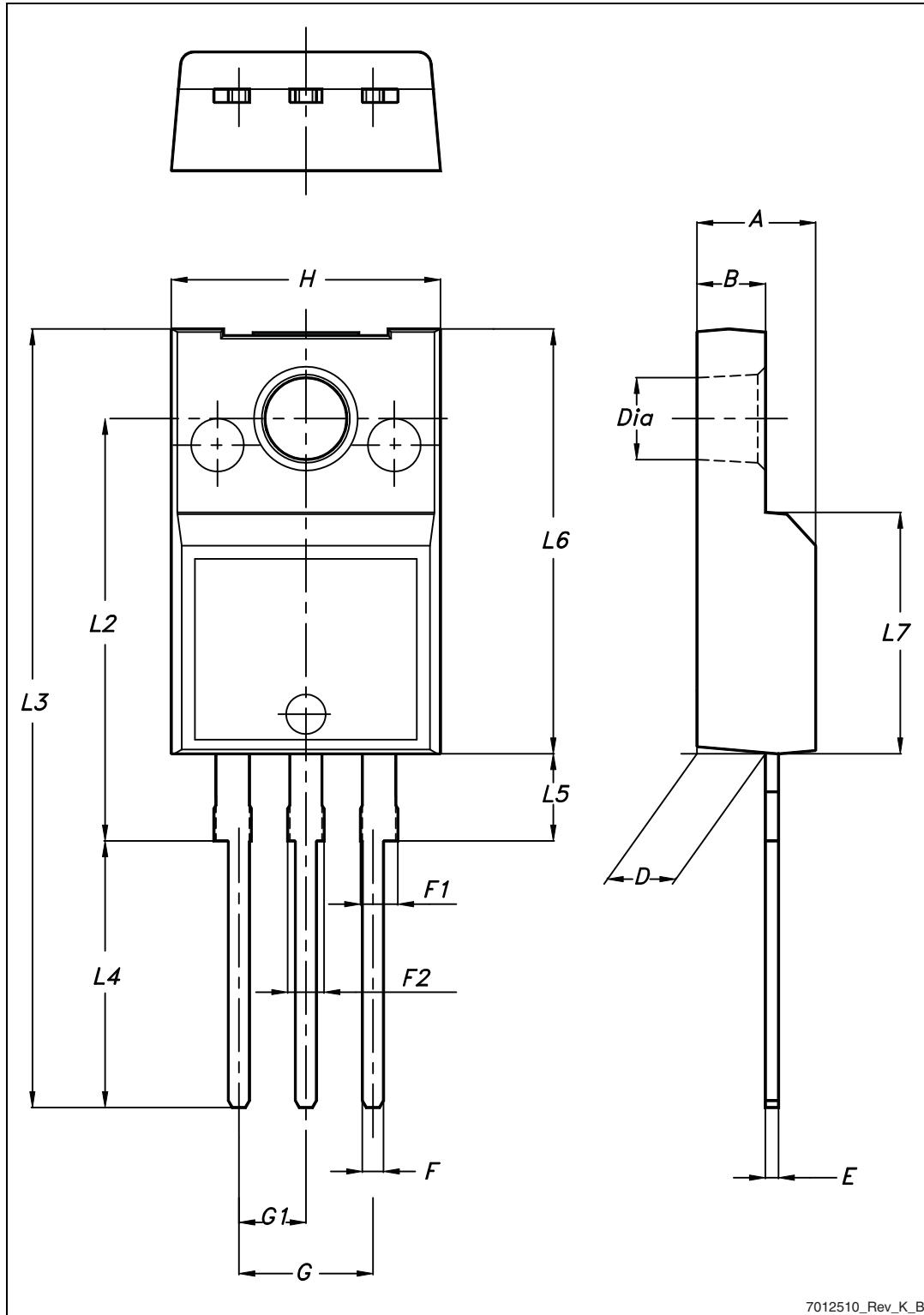
Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.16	2.28	2.40
e1	4.40		4.60
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

**Figure 26. DPAK (TO-252) footprint (a)**

a. All dimensions are in millimeters

## 4.2 TO-220FP package information

Figure 27. TO-220FP package outline

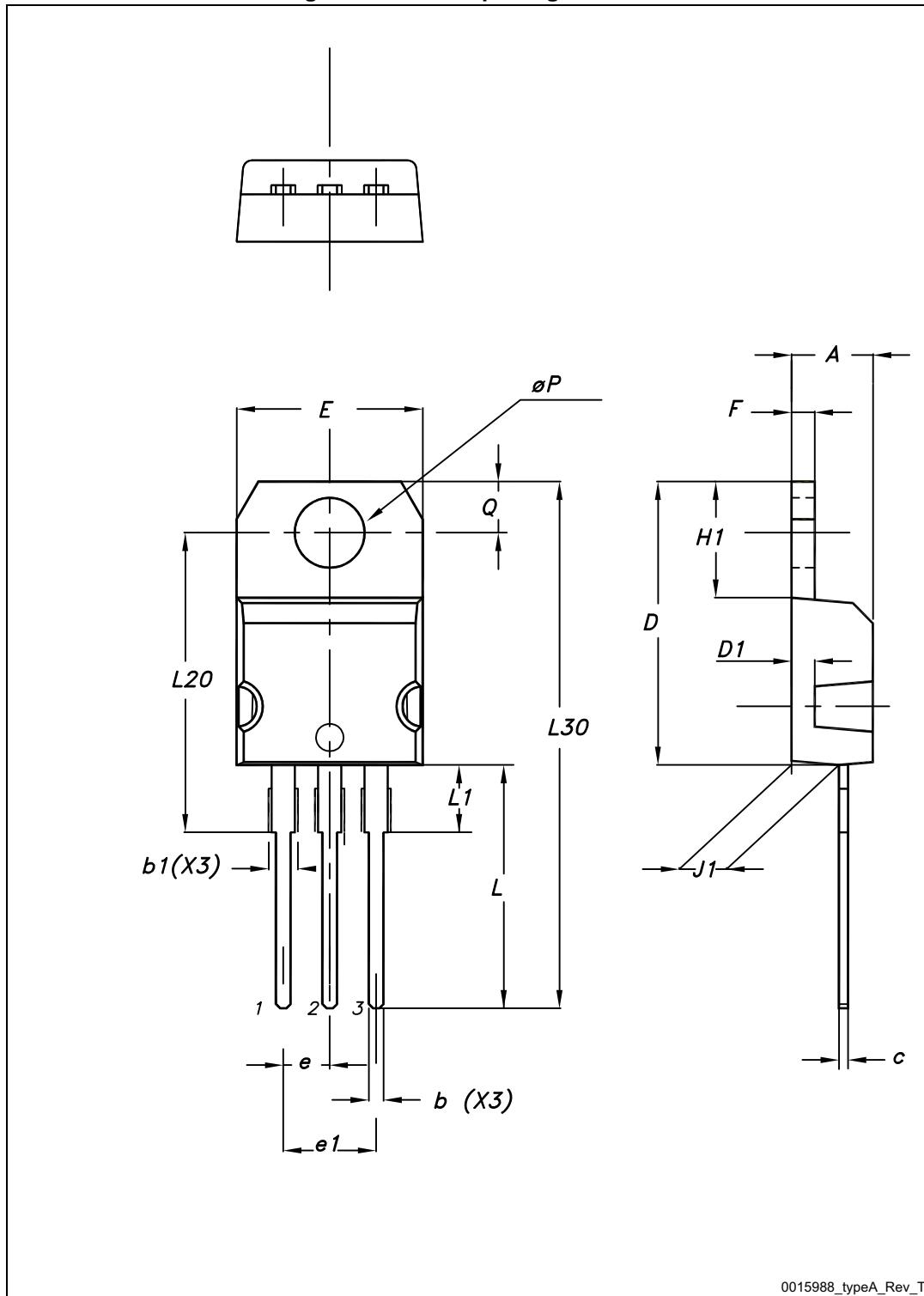


**Table 10. TO-220FP package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

## 4.3 TO-220 package information

Figure 28. TO-220 package outline



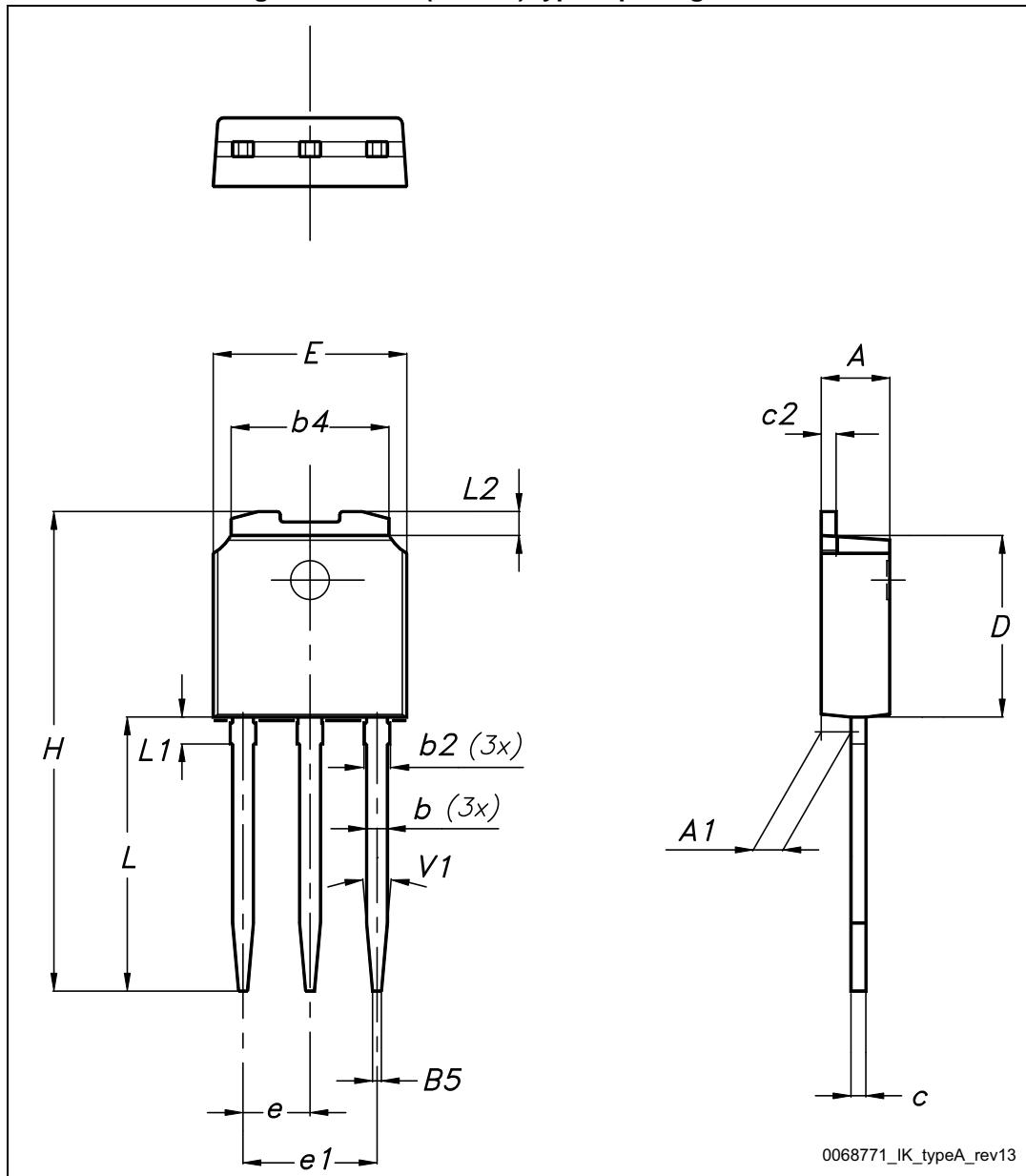
0015988\_typeA\_Rev\_T

**Table 11. TO-220 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

## 4.4 IPAK (TO-251) type A package information

Figure 29. IPAK (TO-251) type A package outline



**Table 12. IPAK (TO-251) type A package mechanical data**

DIM	mm.		
	min.	typ.	max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.30	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10°	

## **5 Packaging information**

**Figure 30. Tape for DPAK**

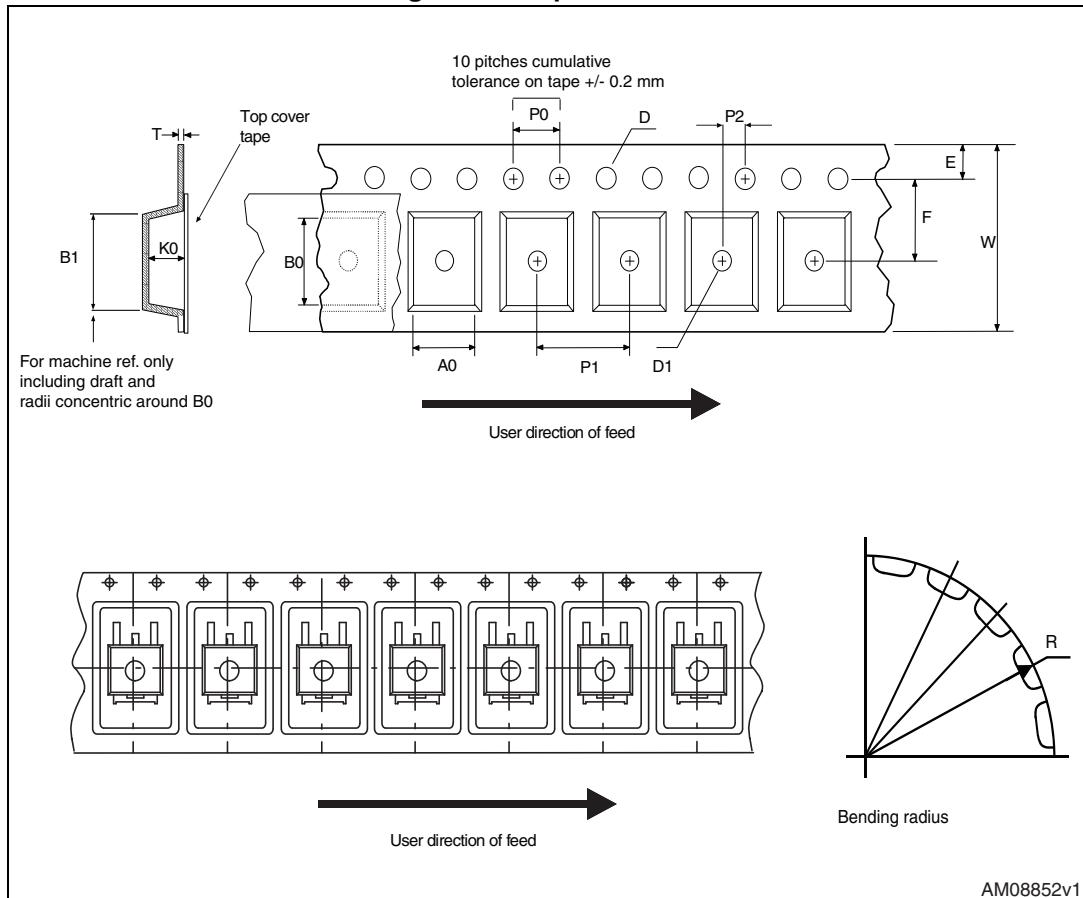


Figure 31. Reel for DPAK

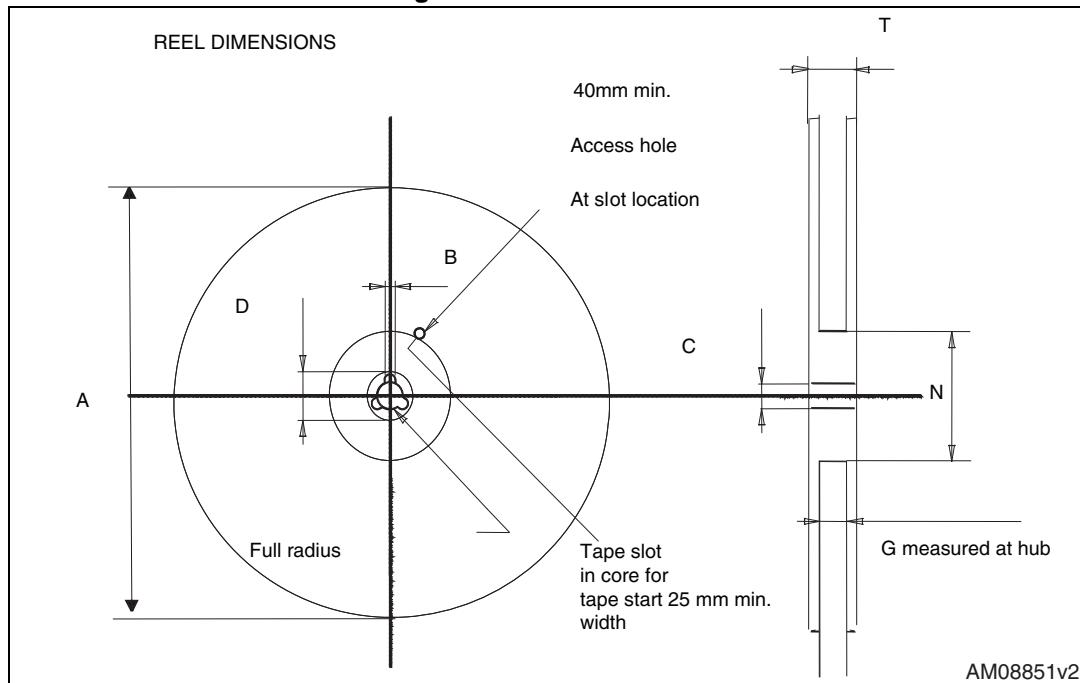


Table 13. DPAK tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1		Base qty.	2500
P1	7.9	8.1		Bulk qty.	2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

## 6 Revision history

Table 14. Document revision history

Date	Revision	Changes
11-Jul-2013	1	First release.
18-Feb-2014	2	<ul style="list-style-type: none"><li>– Added: IPAK package</li><li>– Modified: <math>E_{AS}</math> value in <i>Table 2</i></li><li>– Modified: <math>R_{thj\text{-case}}</math> in <i>Table 3</i></li><li>– Modified: typical values in <i>Table 5, 6 and 7</i></li><li>– Added: <i>Section 2.1: Electrical characteristics (curves)</i></li><li>– Updated: <i>Figure 25, 26 and Table 9</i></li><li>– Added: <i>Table 12</i> and <i>Figure 29</i></li><li>– Minor text changes</li></ul>
25-Sep-2015	3	<ul style="list-style-type: none"><li>– Updated title, features and description in cover page.</li><li>– Updated <i>Figure 10, Figure 11</i> and <i>Section 4: Package information</i>.</li><li>– Minor text changes.</li></ul>

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